



Features

- ▶ Based on core Tracit Technologies: direct bonding and thinning techniques
- ▶ 150 and 200mm capability (scalability to 300mm)

Products/Benefits

Customized BSOI wafer

- ▶ See Thick SOI wafer specsheet

Multi SOI wafer (1)

- ▶ Integration of multilayer devices

Anti-sticking BSOI wafer (2)

- ▶ Prevent sticking effect of membrane obtained after buried oxide release on SOI wafer
- ▶ Increase yield for membrane-based MEMS

D-BSOI™ wafer (3)

Debondable silicon membrane bonded onto a temporary support compatible with microelectronics process

- ▶ Enables processing of thin substrates or membranes

Si-Si wafer

Based on direct silicon bonding (ohmic contact)

- ▶ Combination of highly & low doped layers with sharp doping interface
- ▶ Combination of different crystalline orientations

Device type:

Analog & mixed signal
Discrete power devices
M(O)EMS (accelerometer, membrane...)
Silicon photonics

End-applications:

Automotive
Wireless
Communication

